



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D

*\* : Required Field*

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2017-04-27
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	Giuseppe Vitali Palma	<b>Representative Title</b>	ADG MD Champion
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.


Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
T1235T-8G-TR	7BD1*128SAL1	A	3068	2017-04-27
	Amount	UoM	Unit type	ST ECOPACK Grade
	1380.00	mg	Each	ECOPACK2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
3	245	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin (Sn), matte	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
SIP	10.2-10.5-1.27	3	gull wing	
Comment	D2PAK CLIP			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)
7c-I	Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound

Query : California Prop65 list, dated 27th January 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.137	Die back side metal	99
Lead	4.841	Solder	3508
Lead-Borate Glass	0.441	Glass coating	320

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	78D1*1285A1					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	5.706	mg	supplier	die	Silicon (Si)	7440-21-3		5.033	mg	882054	3647
				supplier	metallization	Gold (Au)	7440-57-5		0.019	mg	3330	14
				supplier	Passivation	Silicon Oxide	7631-86-9		0.029	mg	5082	20
				supplier	back side metallization	Gold (Au)	7440-57-5		0.006	mg	1052	4
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.137	mg	24010	99
				supplier	glass coating	Glass : Aluminium Oxide (Al2O3)	1344-28-1		0.041	mg	7185	30
				JIG - R	glass coating	Lead-Borate Glass	65997-18-4	7c-i-Electrical and e	0.441	mg	77287	320
Leadframe	Copper & its alloys	700.749	mg	supplier	alloy	Copper (Cu)	7440-50-8		700.048	mg	999000	507281
				supplier	alloy	CopperPhosphorous (CuP)	12517-41-8		0.701	mg	1000	508
Soft solder	Solder	5.260	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high mel	4.841	mg	920342	3508
				supplier	solder	Silver (Ag)	7440-22-4		0.131	mg	24905	95
				supplier	solder	Tin (Sn)	7440-31-5		0.262	mg	49810	190
				supplier	solder	flux residue	Proprietary		0.026	mg	4943	19
Encapsulation	Other Organic Materials	630.346	mg	supplier	mold compound	Silica, vitreous	60676-86-0		479.063	mg	760000	347147
				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		64.295	mg	102000	46591
				supplier	mold compound	Phenol resin	9003-35-4		37.821	mg	60000	27407
				supplier	mold compound	Others	Proprietary		31.517	mg	50000	22838
				supplier	mold compound	Metal hydroxide	21645-51-2		12.607	mg	20000	9136
				supplier	mold compound	Carbon black	1333-86-4		5.043	mg	8000	3654
Connections coating	Solder	6.314	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		6.314	mg	1000000	4575
Clip	Copper & its alloys	31.625	mg	supplier	alloy	Copper ( Cu)	7440-50-8		31.625	mg	1000000	22917